



Tentative Specification
Preliminary Specification
Approval Specification

MODEL NO.: G070ACE SUFFIX: LH3

Customer:	
APPROVED BY	SIGNATURE
Name / Title Note	
Please return 1 copy for you signature and comments.	r confirmation with your

Approved By	Checked By	Prepared By



CONTENTS

1.1 OVERVIEW 5 1.2 FEATURE 5 1.3 APPLICATION 5 1.4 GENERAL SPECIFICATIONS 5 1.5 MECHANICAL SPECIFICATIONS 6 2. ABSOLUTE MAXIMUM RATINGS 7 2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 8 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4 BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERRACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26	1. GENERAL DESCRIPTION	5
1.3 APPLICATION 5 1.4 GENERAL SPECIFICATIONS 5 1.5 MECHANICAL SPECIFICATIONS 6 2. ABSOLUTE MAXIMUM RATINGS 7 2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 6 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INIPUT SIGNAL TIMING SPECIFICATIONS 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26 9.2 PACKING	1.1 OVERVIEW	5
1.4 GENERAL SPECIFICATIONS 5 1.5 MECHANICAL SPECIFICATIONS 6 2. ABSOLUTE MAXIMUM RATINGS 7 2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 6 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 16 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26 9.2 PACKING METHOD 26 9.2 PACKING METHOD	1.2 FEATURE	5
1.5 MECHANICAL SPECIFICATIONS 6 2. ABSOLUTE MAXIMUM RATINGS 7 2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 6 2.2.2 BACKLIGHT UNIT 6 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9.2 PACKING METHOD 26 9.2 PACKING METHOD 26 9.2 PACKING METHOD 26 9.2 PACKING METHOD 26 10. DEFINITION OF LABELS 29 10. 1 INX MODULE LABEL<	1.3 APPLICATION	5
2. ABSOLUTE MAXIMUM RATINGS 7 2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 8 3.1 TFT LCD MODULE 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 10 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. 1 INX MODULE LABEL 29 10. 1 INX MODULE LABEL 29	1.4 GENERAL SPECIFICATIONS	5
2.1 ABSOLUTE RATINGS OF ENVIRONMENT 7 2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 8 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 11. 1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.1 ASSEMBLY AND HAND	1.5 MECHANICAL SPECIFICATIONS	6
2.2 ELECTRICAL ABSOLUTE RATINGS 8 2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 8 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING METHOD 26 9.2 PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 10.1 PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31<	2. ABSOLUTE MAXIMUM RATINGS	7
2.2.1 TFT LCD MODULE 8 2.2.2 BACKLIGHT UNIT 8 3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31 <td>2.1 ABSOLUTE RATINGS OF ENVIRONMENT</td> <td>7</td>	2.1 ABSOLUTE RATINGS OF ENVIRONMENT	7
2.2.2 BACKLIGHT UNIT	2.2 ELECTRICAL ABSOLUTE RATINGS	8
3. ELECTRICAL CHARACTERISTICS 9 3.1 TFT LCD MODULE 9 3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10. DEFINITION OF LABELS 29 11.1 PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	2.2.1 TFT LCD MODULE	8
3.1 TFT LCD MODULE	2.2.2 BACKLIGHT UNIT	8
3.2 BACKLIGHT UNIT 10 4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 25 9.1 PACKING SPECIFICATIONS 26 9.1 PACKING METHOD 26 9.3 UN-PACKING METHOD 26 9.3 UN-PACKING METHOD 26 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	3. ELECTRICAL CHARACTERISTICS	9
4. BLOCK DIAGRAM 12 4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	3.1 TFT LCD MODULE	9
4.1 TFT LCD MODULE 12 5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	3.2 BACKLIGHT UNIT	10
5. INPUT TERMINAL PIN ASSIGNMENT 13 5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	4. BLOCK DIAGRAM	12
5.1 TFT LCD MODULE 13 5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	4.1 TFT LCD MODULE	12
5.2 COLOR DATA INPUT ASSIGNMENT 15 6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	5. INPUT TERMINAL PIN ASSIGNMENT	13
6. INTERFACE TIMING 16 6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	5.1 TFT LCD MODULE	13
6.1 INPUT SIGNAL TIMING SPECIFICATIONS 16 6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	5.2 COLOR DATA INPUT ASSIGNMENT	15
6.2 POWER ON/OFF SEQUENCE 18 6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	6. INTERFACE TIMING	16
6.3 SCANNING DIRECTION 20 7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	6.1 INPUT SIGNAL TIMING SPECIFICATIONS	16
7. OPTICAL CHARACTERISTICS 21 7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	6.2 POWER ON/OFF SEQUENCE	18
7.1 TEST CONDITIONS 21 7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	6.3 SCANNING DIRECTION	20
7.2 OPTICAL SPECIFICATIONS 21 8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	7. OPTICAL CHARACTERISTICS	21
8. RELIABILITY TEST CRITERIA 25 9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31		
9. PACKAGING 26 9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	7.2 OPTICAL SPECIFICATIONS	21
9.1 PACKING SPECIFICATIONS 26 9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	8. RELIABILITY TEST CRITERIA	25
9.2 PACKING METHOD 26 9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	9. PACKAGING	26
9.3 UN-PACKING METHOD 28 10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	9.1 PACKING SPECIFICATIONS	26
10. DEFINITION OF LABELS 29 10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	9.2 PACKING METHOD	26
10.1 INX MODULE LABEL 29 11. PRECAUTIONS 30 11.1 ASSEMBLY AND HANDLING PRECAUTIONS 30 11.2 STORAGE PRECAUTIONS 30 11.3 OTHER PRECAUTIONS 31	9.3 UN-PACKING METHOD	28
11. PRECAUTIONS3011.1 ASSEMBLY AND HANDLING PRECAUTIONS3011.2 STORAGE PRECAUTIONS3011.3 OTHER PRECAUTIONS31		
11.1 ASSEMBLY AND HANDLING PRECAUTIONS	10.1 INX MODULE LABEL	29
11.2 STORAGE PRECAUTIONS30 11.3 OTHER PRECAUTIONS31		
11.3 OTHER PRECAUTIONS31	11.1 ASSEMBLY AND HANDLING PRECAUTIONS	30
	11.2 STORAGE PRECAUTIONS	30



. MECHANICAL CHARACTERISTICS	32
Appendix . SYSTEM COVER DESIGN NOTICE	33

Version 0.0 30 March 2022 3 / 41



REVISION HISTORY

Version	Date	Page	Description
Ver 0.0	30 Mar, 2022	All	Tentative Specification was first issued.



1. GENERAL DESCRIPTION

1.1 OVERVIEW

G070ACE-LH3 is a 7" TFT Liquid Crystal Display module with WLED Backlight unit and 30 pins 1ch-LVDS interface. This module supports 800xRGBx480 AAS mode and can display 262k or 16.7M colors.

The PSWG is to establish a set of displays with standard mechanical dimensions and select electrical interface requirements for an industry standard 7" WVGA LCD panel and the LED driving device for Backlight is built in PCBA.

1.2 FEATURE

- WVGA (800 x 480 pixels) resolution
- DE (Data Enable) only mode
- LVDS Interface with 1pixel/clock
- PSWG (Panel Standardization Working Group)
- Wide operating temperature.
- RoHS compliance

1.3 APPLICATION

- -TFT LCD Monitor
- Factory Application
- Amusement

1.4 GENERAL SPECIFICATIONS

Item	Specification	Unit	Note
Active Area	152.4 (H) x 91.44 (V) (7" diagonal)	mm	(1)
Driver Element	a-Si TFT active matrix	-	-
Pixel Number	800 x R.G.B. x 480	pixel	-
Pixel Pitch	0.1905 (H) x 0.1905 (V)	mm	-
Pixel Arrangement	RGB vertical Stripe	-	-
Display Colors	16.7M / 262K	color	-
Display Mode	Normally Black	-	-
Surface Treatment	Hard Coating (3H), Anti-Glare	-	-
Module Power Consumption	Total 3.15 W @ cell 0.45 W, BL 2.7 W	W	Тур.



1.5 MECHANICAL SPECIFICATIONS

Item		Min.	Тур.	Max.	Unit	Note
	Horizontal (H)	164.5	165	165.5	mm	
Module Size	Vertical (V)	103.5	104	104.5	mm	(1)
	Thickness (T)	8.13	8.63	9.13	mm	
Bezel Area	Horizontal	154.3	154.60	154.9	mm	
bezei Alea	Vertical	93.34	93.64	93.94	mm	
Active Area	Horizontal	-	152.4	-	mm	
Active Area	Vertical	-	91.44	-	mm	
Weight			(152)		g	

Note (1)Please refer to the attached drawings for more information of front and back outline dimensions.



2. ABSOLUTE MAXIMUM RATINGS

2.1 ABSOLUTE RATINGS OF ENVIRONMENT

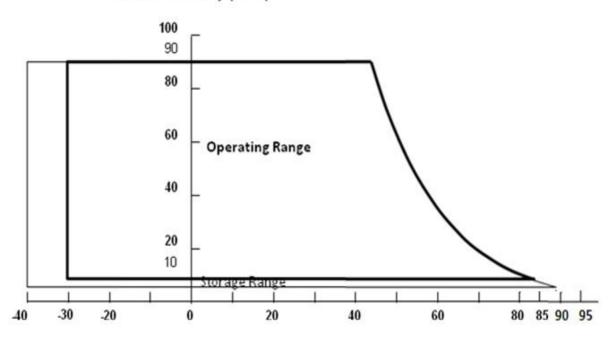
Item	Symbol	Va	Unit	Note	
iteiii	Syllibol	Min.	Max.	Offic	Note
Storage Temperature	Tst	-40	(85)	$^{\circ}\!\mathbb{C}$	(4)(2)
Operating Ambient Temperature	Тор	-30	(85)	$^{\circ}\!\mathbb{C}$	(1)(2)

Note (1)

- (a) 90 %RH Max.
- (b) Wet-bulb temperature should be 39 °C Max.
- (c) No condensation.

Note (2) Panel surface temperature should be $0^{\circ}\mathbb{C}$ min. and $65^{\circ}\mathbb{C}$ max under Vcc=5.0V, fr =60Hz, typical LED string current, $25^{\circ}\mathbb{C}$ ambient temperature, and no humidity control . Any condition of ambient operating temperature ,the surface of active area should be keeping not higher than $65^{\circ}\mathbb{C}$.

Relative Humidity (%RH)





2.2 ELECTRICAL ABSOLUTE RATINGS

2.2.1 TFT LCD MODULE

Item	Symbol	Val	ue	Unit Note	Noto	
item	Syllibol	Min.	Max.	Offic	Note	
Power Supply Voltage	Vcc	-0.3	3.6	V	(1)	
Logic Input Voltage	V _{IN}	-0.3	3.6	V	(1)	

2.2.2 BACKLIGHT UNIT

Itom	Symbol	Va	lue	Unit	Note	
Item	Symbol	Min.	Max.	Ullit	Note	
Converter Voltage	Vi	0	18.0	V	(1), (2)	
Enable Voltage	EN		7	V		
Backlight Adjust	Dimming		7	V		

Note (1) Permanent damage to the device may occur if maximum values are exceeded. Function operation should be restricted to the conditions described under Normal Operating Conditions.

Note (2) Specified values are for LED (Refer to 3.2 for further information).



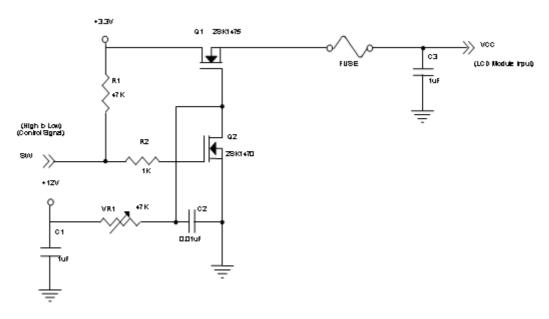
3. ELECTRICAL CHARACTERISTICS

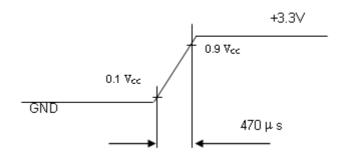
3.1 TFT LCD MODULE

Doromotor	Parameter			Value			Note
Faidifielei	Symbol	Min.	Тур.	Max.	Unit	Note	
Power Supply Vo	ltage	Vcc	3.0	3.3	3.6	V	-
Ripple Voltage	е	V_{RP}	-	-	100	mVp-p	-
Rush Current	t	I _{RUSH}	-	-	2	Α	(2)
Dower Supply Current	White	lcc	-	135	200	mA	(3)a
Power Supply Current	Black	ICC	-	85	135	mA	(3)b
LVDS differential inpu	it voltage	Vid	200	-	600	mV	
LVDS common input	voltage	Vic	1.0	1.2	1.4	V	
Differential Input Voltage for	"H" Level	V_{TH}	-	-	+100	mV	-
LVDS Receiver Threshold	"L" Level	V_{TL}	-100	-	-	mV	-
Logic Input Voltage	"H" Level	V_{IH}	2.6	-	Vcc	٧	
Logic Input Voltage	"L" Level	V _{IL}	0	-	0.7	V	
Terminating Resi	stor	R _T	-	100	-	Ohm	-

Note (1)The module should be always operated within above ranges.

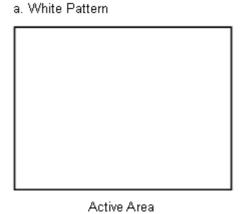
Note (2)Measurement Conditions:







Note (3) The specified power supply current is under the conditions at V_{CC} =3.3V, Ta = 25 \pm 2 $^{\circ}$ C, DC Current and f_v = 60 Hz, whereas a power dissipation check pattern below is displayed.



b. Black Pattern



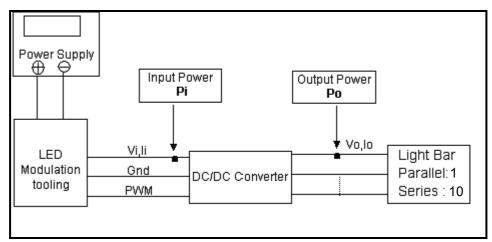
Active Area

3.2 BACKLIGHT UNIT

Paramo	Symbol		Value		Unit	Note	
i arann	Symbol	Min.	Тур.	Max.	Offic	NOLE	
Converter Power S	Supply Voltage	LED_Vin	10.8	12.0	13.2	V	
Converter Input F	Ripple Voltage	V_{iRP}	-	-	500	mV	
Converter Power S	Supply Current	li	0.18	0.22	0.3	Α	@LED_Vin= 12V Duty=100%
Converter Input I	Rush Current	lirsh			3	Α	@LED_Vin rising = 1mS(Vi=12V)
Input Power Co	onsumption	Pi	-	2.7	3.3	W	(1)
EN Control Level	Backlight on	ENLED	2.0	3.3	5.0	V	EN Control Level
EN Control Level	Backlight off	(BLON)	0	-	0.3	V	
PWM Control Level	PWM High Level	Dimming	2.0		5.0	V	PWM Control Level
PVVIVI CONITOI Level	PWM Low Level	(E_PWM)	0		0.15	V	
PWN Noise	Range	VNoise	i	-	0.1	V	
PWM Control	Frequency	f_{PWM}	190	200	20K	Hz	(3)
DIAMA Dimming Co				-	100	%	(3), @ 190Hz <f<sub>PWM<1kHz</f<sub>
PWM Dimming Co	-	20	-	100	%	(3), @ 1kHz≦f _{PWM} <20kHz	
LED Life	Time	L _{LED}	50,000		-	Hrs	(2)



Note (1)LED current is measured by utilizing a high frequency current meter as shown below:



- Note (2) The lifetime of LED is estimated data and defined as the time when it continues to operate under the conditions at Ta = 25 ±2 °C and Duty 100% until the brightness becomes ≤ 50% of its original value.

 Operating LED at high temperature condition will reduce life time and lead to color shift.
- Note (3) At 190 ~1kHz PWM control frequency, duty ratio range is restricted from 5% to 100%.

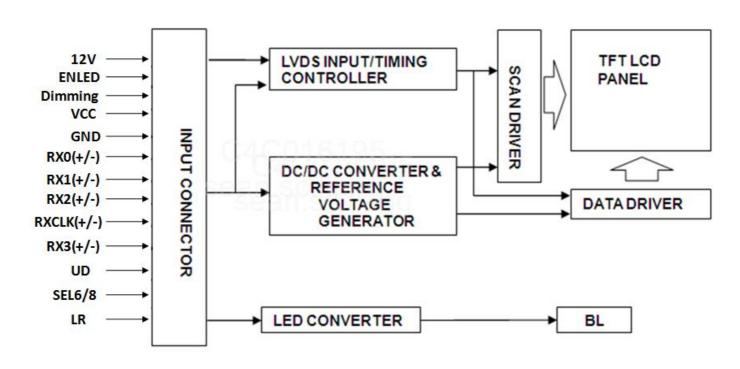
 1K ~20kHz PWM control frequency, duty ratio range is restricted from 20% to 100%.

 If PWM control frequency is applied in the range from 1KHz to 20KHZ, The "non-linear" phenomenon on the Backlight Unit may be found. So It's a **suggestion** that PWM control frequency should be **less than 1KHz**.



4. BLOCK DIAGRAM

4.1 TFT LCD MODULE





5. INPUT TERMINAL PIN ASSIGNMENT

5.1 TFT LCD MODULE

Pin No.	Symbol	Function	Polarity	Note
1	12V	LED power		-
2	12V	LED power		-
3	12V	LED power		-
4	12V	LED power		-
5	ENLED	Enable pin		=
6	Dimming	Backlight Adjust		-
7	NC	No Conncetion (Reserve for INX test)		(4)
8	NC	No Conncetion (Reserve for INX test)		(4)
9	VCC	Power supply: +3.3V		-
10	VCC	Power supply: +3.3V		-
11	GND	Ground		-
12	GND	Ground		-
13	RX0-	Negative transmission data of pixel 0	Negative	-
14	RX0+	Positive transmission data of pixel 0	Positive	-
15	GND	Ground		-
16	RX1-	Negative transmission data of pixel 1	Negative	-
17	RX1+	Positive transmission data of pixel 1	Positive	-
18	GND	Ground		-
19	RX2-	Negative transmission data of pixel 2	Negative	-
20	RX2+	Positive transmission data of pixel 2	Positive	-
21	GND	Ground		-
22	RXCLK-	Negative of clock	Negative	-
23	RXCLK+	Positive of clock	Positive	-
24	GND	Ground		=
25	RX3-	Negative transmission data of pixel 3	Negative	=
26	RX3+	Positive transmission data of pixel 3	Positive	-
_		Gate Driver Up/Down scan control.		
27	UD	When UD=H, reverse scan		(3)
		When UD=L, normal scan		
00	051.0/0	LVDS 6/8 bit select function control,		(0)
28	SEL6/8	Low → 6 bit Input Mode		(3)
		High or NC → 8bit Input Mode		
29	LR	Source Driver Right/ Left scan control. When LR=H, normal scan		(3)
29	LIX	When LR=L, reverse scan		(3)
30	GND	Ground		
30	GND	Ground		

Note (1) Connector Part No.: Starconn 093G30-B0001A-G4.or P-TWO 187114-30091

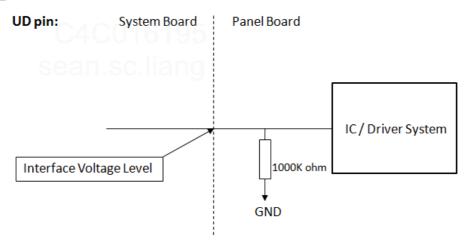
Note (2) User's connector Part No:

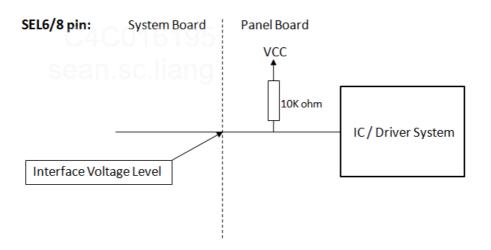
Mating Wire Cable Connector Part No. :FI-X30H (JAE) or FI-X30HL (JAE)

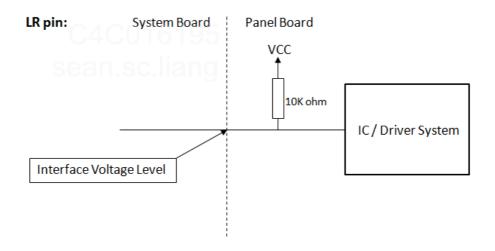
Note (3) "Low" stands for 0V. "High" stands for 3.3V

Note (4) Pin7, Pin8 input signals should be set to no connection or ground, this module











5.2 COLOR DATA INPUT ASSIGNMENT

The brightness of each primary color (red, green and blue) is based on the 8-bit gray scale data input for the color. The higher the binary input the brighter the color. The table below provides the assignment of color versus data input.

										ı		D	ata	_	nal										
	Color				R									een								ue			
	T	R7	R6	R5	R4	R3	R2	R1	R0	G7	G6	G5	G4	G3	G2	G1	G0	B7	B6	B5	B4	ВЗ	B2	B1	B0
	Black	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
Basic	Blue	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
Colors	Cyan	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Magenta	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1
	Yellow	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	White	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1	1
	Red(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(1)	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Gray	Red(2)	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Red	Red(253)	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
INCU	Red(254)	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Red(255)	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(0)/Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Green(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0
Gray	Green(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0	0	0	0	0	0	0	0	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Green	Green(253)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1	0	0	0	0	0	0	0	0
GICCII	Green(254)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0	0
	Green(255)	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1	0	0	0	0	0	0	0	0
	Blue(0) / Dark	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0
	Blue(1)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1
Gray	Blue(2)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	0
Scale	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Of	: : : : : : : : : : : : : : : : : : : :	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:	:
Blue	Blue(253)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	0	1
	Blue(254)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	0
	Blue(255)	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	0	1	1	1	1	1	1	1	1

Note (1)0: Low Level Voltage, 1: High Level Voltage



6. INTERFACE TIMING

6.1 INPUT SIGNAL TIMING SPECIFICATIONS

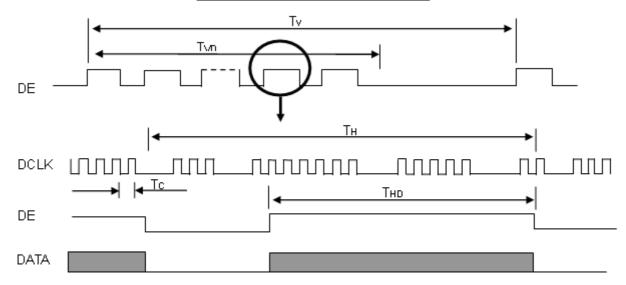
The input signal timing specifications are shown as the following table and timing diagram.

Signal	Item	Symbol	Min.	Тур.	Max.	Unit	Note	
	Frequency	Fc	25.2	25.4	35.7	MHz	-	
	Period	Tc		39.37		ns		
	Input cycle to cycle jitter	T _{rcl}	-0.02*Tc	ı	0.02*Tc	ns	(a)	
LVDS Clock	Input Clock to data skew	TLVCCS	-0.02*Tc	-	0.02*Tc	ps	(b)	
	Spread spectrum modulation range	F _{clkin_mod}	-	ı	1.02*F _c	MHz	(c)	
	Spread spectrum modulation frequency	F _{SSM}	23	-	93	KHz	(c)	
	Frame Rate	Fr	-	60	-	Hz	-	
Vertical Display	Total	T_v	488	490	611	T_h	$Tv=T_{vd}+T_{vb}$	
Term	Active Display	T_{vd}	480	480	480	T_h	-	
	Blank	T_{vb}	8	10	131	T_h	-	
Harimantal Diamlar	Total	T _h	860	864	974	T _c	$T_h = T_{hd} + T_{hb}$	
Horizontal Display Term	Active Display	T_{hd}	800	800	800	T _c	-	
101111	Blank	T_{hb}	60	64	174	T _c	-	

Note (1) Because this module is operated by DE only mode, Hsync and Vsync input signals should be set to low logic level or ground. Otherwise, this module would operate abnormally.

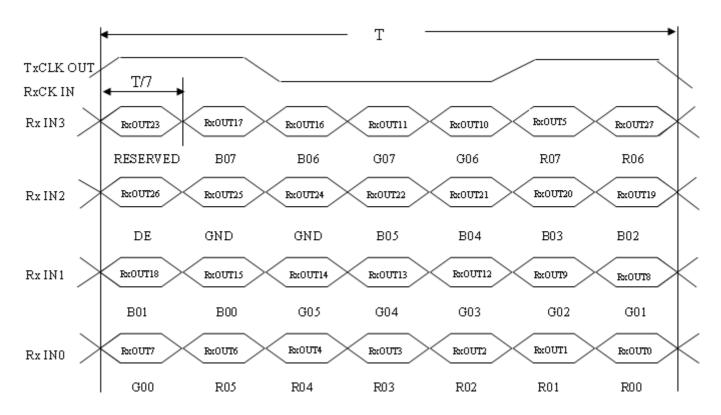
Note (2) The Tv(Tvd+Tvb) must be integer, otherwise, the module would operate abnormally.

INPUT SIGNAL TIMING DIAGRAM

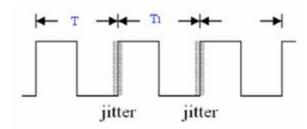




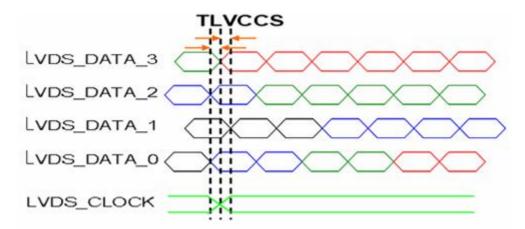
TIMING DIAGRAM of LVDS



Note (a) The input clock cycle-to-cycle jitter is defined as below figures. $T_{rcl} = I T1 - TI$

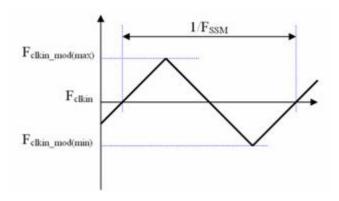


Note (b) Input Clock to data skew is defined as below figures.



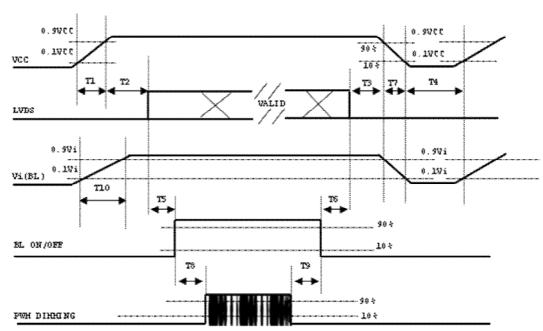


Note (c) The SSCG (Spread spectrum clock generator) is defined as below figures.



6.2 POWER ON/OFF SEQUENCE

To prevent a latch-up or DC operation of LCD assembly, the power on/off sequence should be as the diagram below.



Doromotor		Units				
Parameter	Min	Min Typ Max				
T1	0.5	1	10	ms		
T2	0	-	50	ms		
Т3	0	-	50	ms		
T4	500	-	-	ms		
T5	450	-	-	ms		
T6	200	1	-	ms		
T7	10	-	100	ms		

Version 0.0 30 March 2022 18 / 41



, , , , , , , , , , , , , , , , , , , 				
Т8	10	-	-	ms
Т9	10	-	-	ms
T10	20	-	50	ms

Note

- (1)The supply voltage of the external system for the module input should be the same as the definition of Vcc.
- (2)When the backlight turns on before the LCD operation of the LCD turns off, the display may momentarily become abnormal screen.
- (3)In case of VCC = off level, please keep the level of input signals on the low or keep a high impedance.
- (4)T4 should be measured after the module has been fully discharged between power off and on period.
- (5)Interface signal shall not be kept at high impedance when the power is on.
- (6)INX won't take any responsibility for the products which are damaged by the customers not following the Power Sequence.

There might be slight electronic noise when LCD is turned off (even backlight unit is also off). To avoid this symptom, we suggest "Vcc falling timing" to follow "T7 spec".





6.3 SCANNING DIRECTION

The following figures show the image see from the front view. The arrow indicates the direction of scan.

Fig.1 Normal Scan



Fig.2 Reverse Scan



PCBA on the bottom side

PCBA on the bottom side

- Fig. 1 Normal scan (pin 27, UD = Low, pin 29 LR = High)
- Fig. 2 Reverse scan (pin 27, UD = High, pin 29 LR = Low)



7. OPTICAL CHARACTERISTICS

7.1 TEST CONDITIONS

Item	Symbol	Value	Unit
Ambient Temperature	Та	25±2	оС
Ambient Humidity	На	50±10	%RH
Supply Voltage	Accordin	ng to typical value and tole	erance in
Input Signal	"ELE	CTRICAL CHARACTERIS	STICS"
PWM Duty Ratio	D	100	%

7.2 OPTICAL SPECIFICATIONS

The relative measurement methods of optical characteristics are shown here and all items are measured at the center point of screen unless otherwise noted. The following items should be measured under the test conditions described above and stable conditions shown in Note (5).

Iter	n	Symbol	Condition	Min.	Тур.	Max.	Unit	Note
	Red	Rx			(0.58)			
	Red	Ry			(0.330)			
	Green	Gx			(0.334)			
Color	Green	Gy		Тур –	(0.600)	Typ +		(1) (5)
Chromaticity	Blue	Bx	θX=0°, θY =0°	0.05	(0.150)	0.05	-	(1), (5)
	blue	Ву	Grayscale Maximum		(0.054)			
)	Wx			0.313			
	White	Wy			0.329			
Center Lumina	nce of White	LC		400	500		cd/m ²	(4), (5)
Contrast	Ratio	CR		600	800			(2), (5)
Pospopo	o Timo	TR	0V-0° 0V -0°	-	13	-	mo	(2)
Respons	e nine	TF	θX=0°, θY =0°	ı	12	-	ms	(3)
White Va	White Variation		θX=0°, θY =0°	70	-	-	%	(5), (6)
	Horizontal	θX+		80	89	-		
Viouing Anglo	Horizoniai	θX-	CR≧10	80	89	-	Dog	(1) (E)
Viewing Angle	Vertical	θΥ+	UN≦ IU	80	89	-	Deg.	(1), (5)
	vertical	θY-		80	89	-		

Definition:

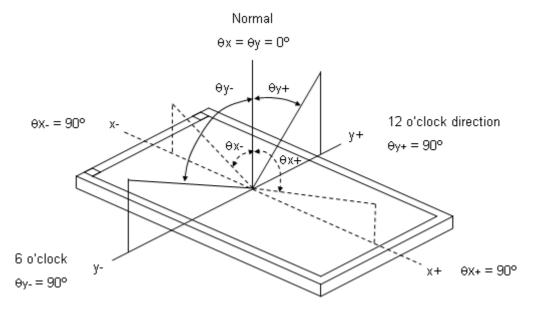
Grayscale Maximum: Grayscale 255 (10 bits: grayscale 1023; 8 bits: grayscale 255; 6 bits: grayscale 63)

White: Luminance of Grayscale Maximum (All R,G,B)

Black: Luminance of grayscale 0 (All R,G,B)



Note (1)Definition of Viewing Angle (θx , θy):

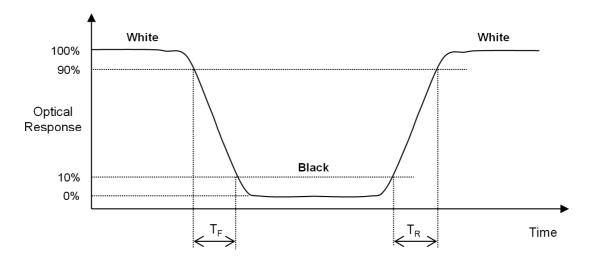


Note (2)Definition of Contrast Ratio (CR):

The contrast ratio can be calculated by the following expression at center point.

Contrast Ratio (CR) = White / Black

Note (3)Definition of Response Time (T_R, T_F) :





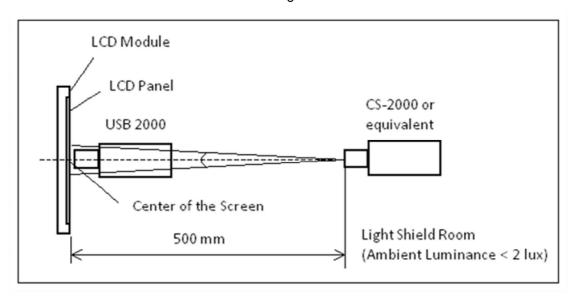


Note (4) Definition of Luminance of White (L_C) :

Measure the luminance of White at center point.

Note (5) Measurement Setup:

The LCD module should be stabilized at given temperature to avoid abrupt temperature change during measuring. In order to stabilize the luminance, the measurement should be executed after lighting Backlight for 40 minutes in a windless room. The measurement placement of module should be in accordance with module drawing.



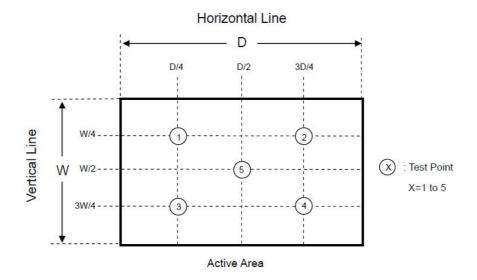
Note (6) Definition of White Variation (δW):

Measure the luminance of White at 5 points.

Luminance of White : L(X), where X is from 1 to 5.

$$\delta W = \frac{Minimum [L(1) to L(5)]}{Maximum [L(1) to L(5)]} \times 100\%$$







8. RELIABILITY TEST CRITERIA

Test Item	Test Condition	Note
High Temperature Storage Test	(85°C, 240 hours)	
Low Temperature Storage Test	-40°C, 240 hours	
Thermal Shock Storage Test	-30°C, 0.5hour ←→80°C, 0.5hour; 1hour/cycle,100cycles	(1),(2)
High Temperature Operation Test	(85°C, 240 hours)	(4),(5)
Low Temperature Operation Test	-30°C, 240 hours	() ()
High Temperature & High Humidity Operation Test	60℃, RH 90%, 240 hours	
Shock (Non-Operating)	50G, 11ms, half sine wave, 1 time for ± X, ± Y, ± Z	(2), (3)
Vibration (Non-Operating)	1.5G, 10 ~ 300 Hz, 10min/cycle, 3 cycles each X, Y, Z	

- Note (1)There should be no condensation on the surface of panel during test,
- Note (2) Temperature of panel display surface area should be 85°C Max.
- Note (3) At testing Vibration and Shock, the fixture in holding the module has to be hard and rigid enough so that the module would not be twisted or bent by the fixture.
- Note (4) In the standard conditions, there is no function failure issue occurred. All the cosmetic specification is judged before reliability test.
- Note (5) Before cosmetic and function test, the product must have enough recovery time, at least 24 hours at room temperature.





9. PACKAGING

9.1 PACKING SPECIFICATIONS

- (1) 34 pcs LCD modules / 1 Box
- (2) Box dimensions: 465 (L) X 362 (W) X 314 (H) mm
- (3) Weight: approximately TBD Kg (34modules per box)

9.2 PACKING METHOD

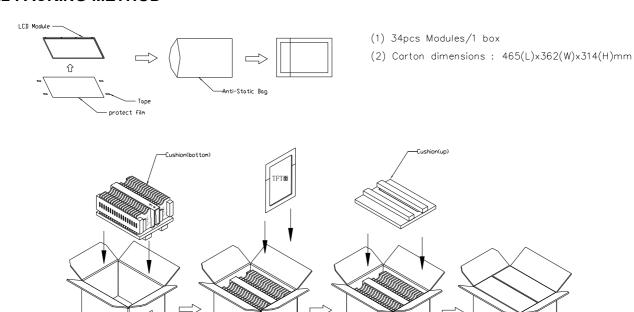


Figure. 9-1 Packing method



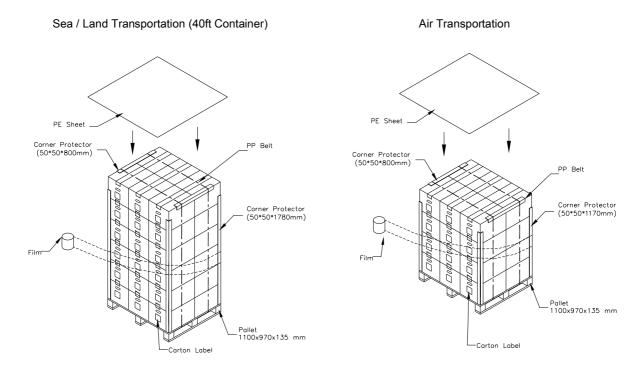


Figure. 9-2 Packing method



9.3 UN-PACKING METHOD

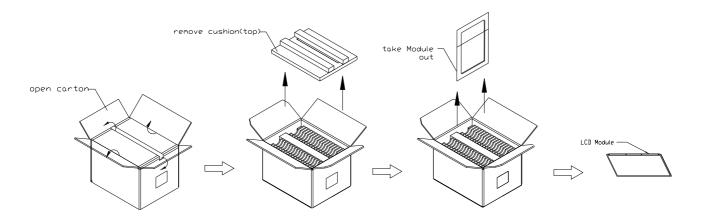


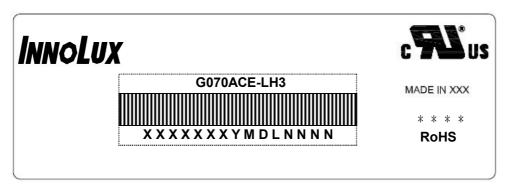
Figure. 9-3 UN-Packing method



10. DEFINITION OF LABELS

10.1 INX MODULE LABEL

The barcode nameplate is pasted on each module as illustration, and its definitions are as following explanation.

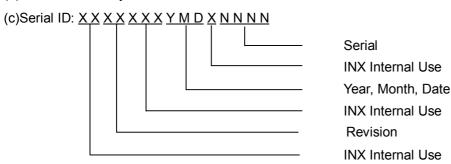




Note (1) Safety Compliance(UL logo) will open after C1 version.

(a)Model Name: G070ACE-LH3

(b)* * * * : Factory ID



Serial ID includes the information as below:

(a) Manufactured Date: Year: 1~9, for 2021~2029

Month: 1~9, A~C, for Jan. ~ Dec.

Day: 1~9, A~Y, for 1st to 31st, exclude I, O and U

(b) Revision Code: cover all the change

(c) Serial No.: Manufacturing sequence of product

INNOLUX 群創光電

PRODUCT SPECIFICATION

11. PRECAUTIONS

11.1 ASSEMBLY AND HANDLING PRECAUTIONS

- (1) The module should be assembled into the system firmly by using every mounting hole. Be careful not to twist or bend the module.
- (2) While assembling or installing modules, it can only be in the clean area. The dust and oil may cause electrical short or damage the polarizer.
- (3) Use fingerstalls or soft gloves in order to keep display clean during the incoming inspection and assembly process.
- (4) Do not press or scratch the surface harder than a HB pencil lead on the panel because the polarizer is very soft and easily scratched.
- (5) If the surface of the polarizer is dirty, please clean it by some absorbent cotton or soft cloth. Do not use Ketone type materials (ex. Acetone), Ethyl alcohol, Toluene, Ethyl acid or Methyl chloride. It might permanently damage the polarizer due to chemical reaction.
- (6) Wipe off water droplets or oil immediately. Staining and discoloration may occur if they left on panel for a long time.
- (7) If the liquid crystal material leaks from the panel, it should be kept away from the eyes or mouth. In case of contacting with hands, legs or clothes, it must be washed away thoroughly with soap.
- (8) Protect the module from static electricity, it may cause damage to the C-MOS Gate Array IC.
- (9) Do not disassemble the module.
- (10) Do not pull or fold the lamp wire.
- (11) Pins of I/F connector should not be touched directly with bare hands.

11.2 STORAGE PRECAUTIONS

- (1)When storing for a long time, the following precautions are necessary.
 - (a) Store them in a dark place. Do not expose the module to sunlight or fluorescent light. Keep the temperature between 5°C and 30°C at humidity 50+-10%RH.
 - (b) The polarizer surface should not come in contact with any other object.
 - (c) It is recommended that they be stored in the container in which they were shipped.
 - (d) Storage condition is guaranteed under packing conditions.
 - (e)The phase transition of Liquid Crystal in the condition of the low or high storage temperature will be recovered when the LCD module returns to the normal condition
- (2) High temperature or humidity may reduce the performance of module. Please store LCD module within the specified storage conditions.
- (3)It is dangerous that moisture come into or contacted the LCD module, because the moisture may damage LCD module when it is operating.
- (4)It may reduce the display quality if the ambient temperature is lower than 10 °C. For example, the response time will become slowly, and the starting voltage of lamp will be higher than the room temperature.

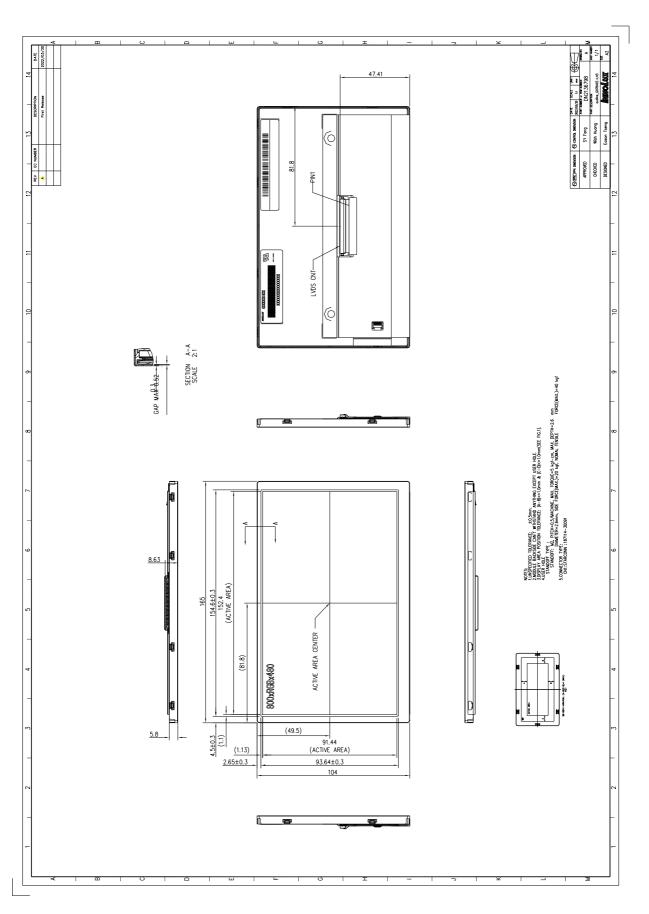


11.3 OTHER PRECAUTIONS

- (1) Normal operating condition
 - (a) Display pattern: dynamic pattern (Real display)(Note) Long-term static display can cause image sticking.
- (2) Operating usages to protect against image sticking due to long-term static display
 - (a) Suitable operating time: under 16 hours a day.
 - (b) Static information display recommended to use with moving image.
 - (c)Cycling display between 5 minutes' information(static) display and 10 seconds' moving image.
- (3) Abnormal condition just means conditions except normal condition.

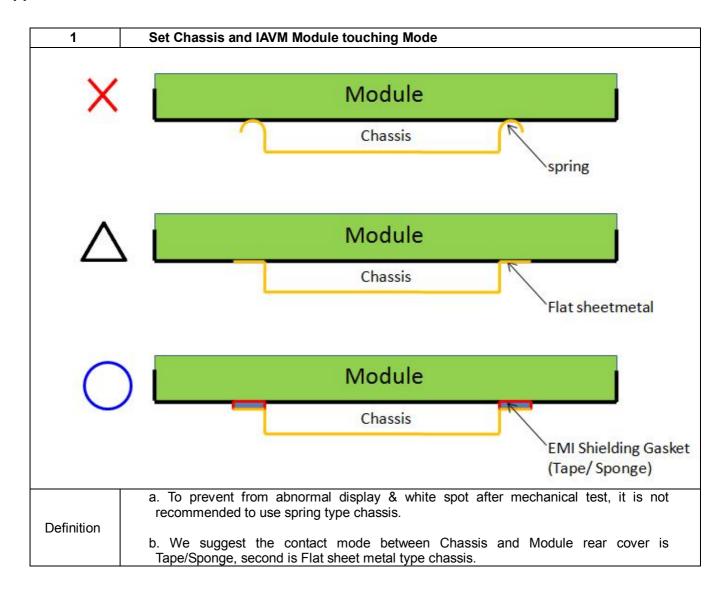


. MECHANICAL CHARACTERISTICS

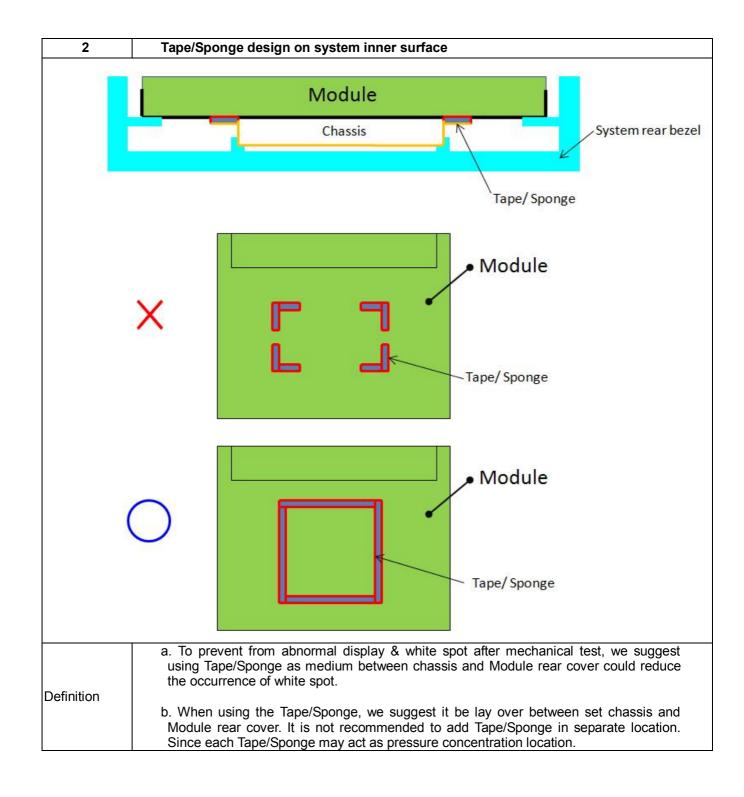




Appendix . SYSTEM COVER DESIGN NOTICE

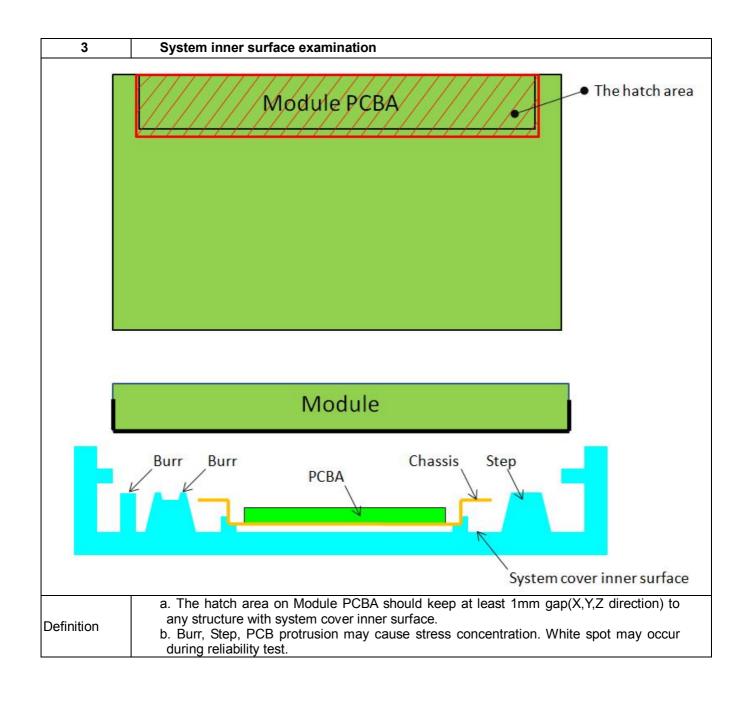




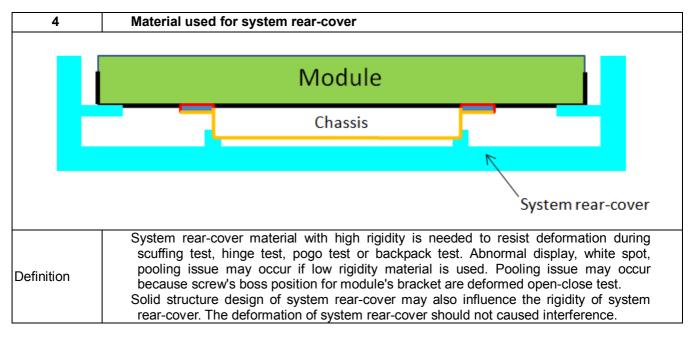


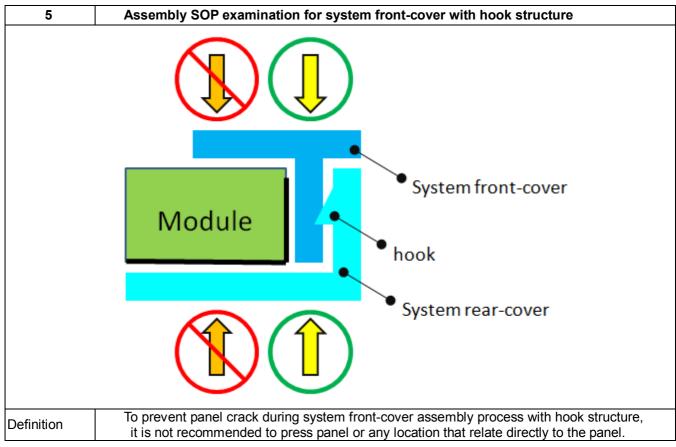
Version 0.0 30 March 2022 34 / 41





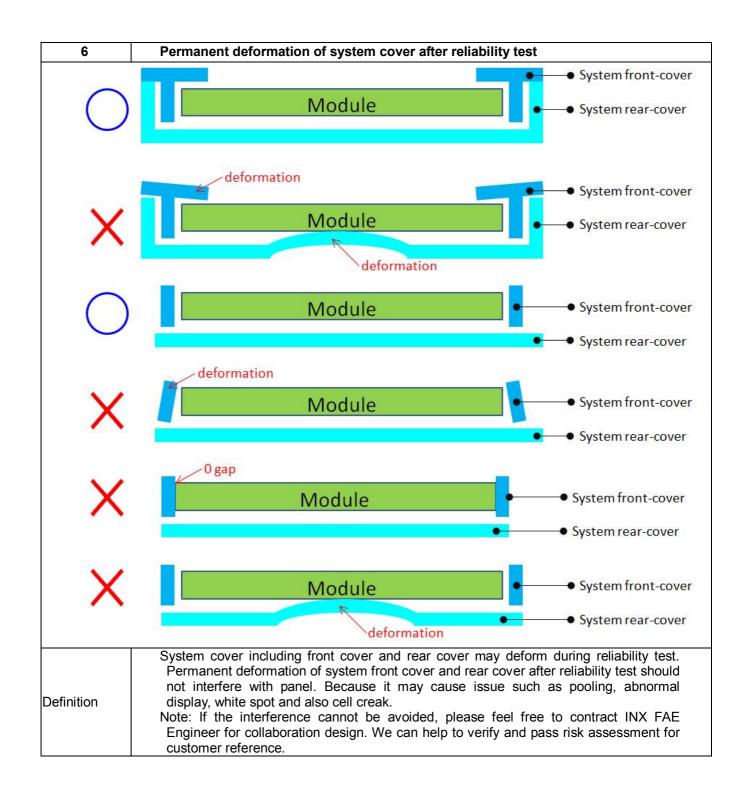




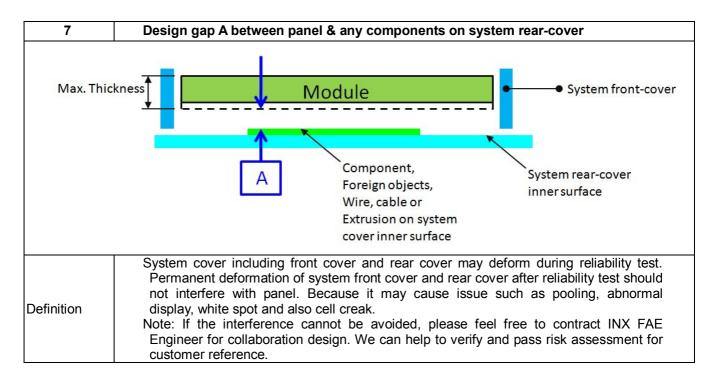


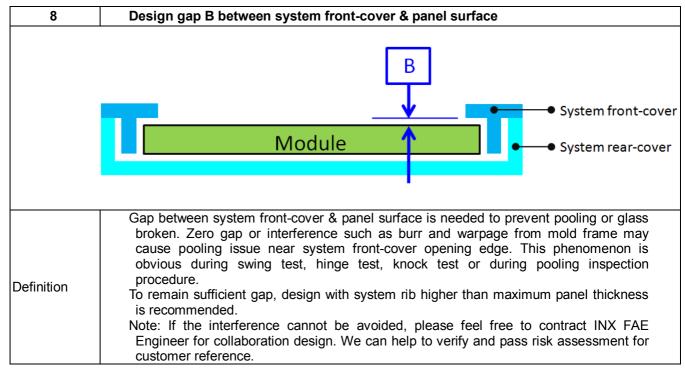
Version 0.0 30 March 2022 36 / 41





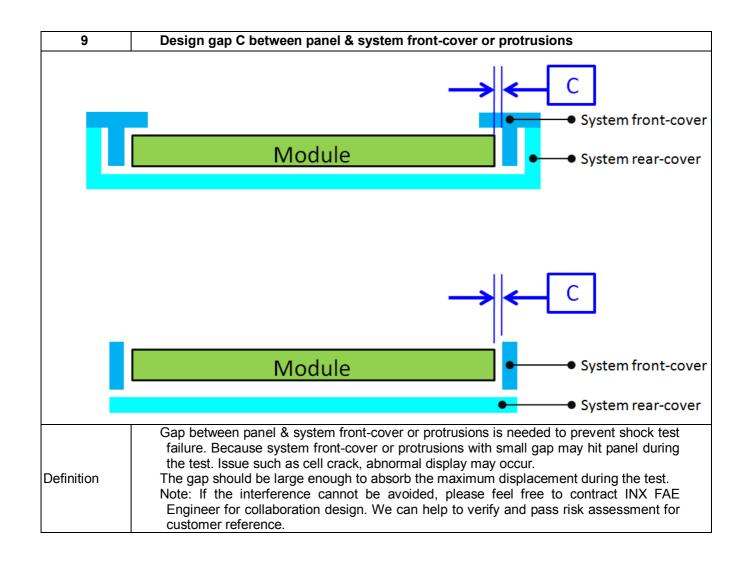






Version 0.0 30 March 2022 38 / 41

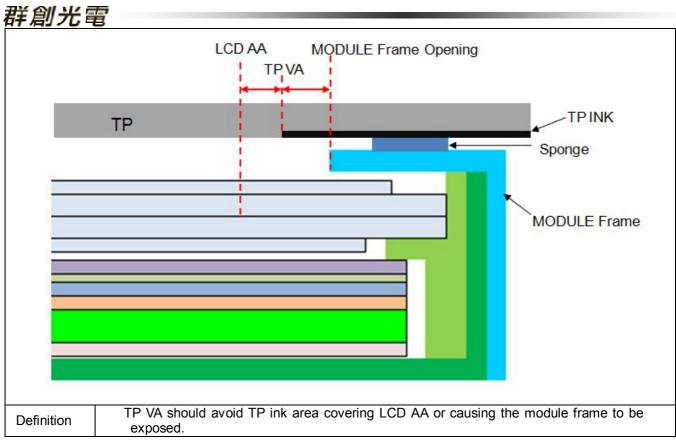




10	Design distance between TP AA to LCD AA
	=

Version 0.0 30 March 2022 39 / 41





11	Use OCR Lamination



